

FQP11N40C / FQPF11N40C

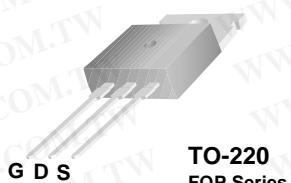
N-Channel QFET MOSFET

400 V, 10.5 A, 530 mΩ

勝特力材料 886-3-5753170
胜特力电子(上海) 86-21-34970699
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Description

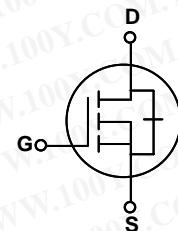
This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.



TO-220
FQP Series



TO-220F
FQPF Series



Features

- 10.5 A, 400 V, $R_{DS(on)}$ = 530 mΩ (Max) @ $V_{GS} = 10$ V, $I_D = 5.25$ A
- Low Gate Charge (Typ. 28 nC)
- Low Crss (Typ. 85 pF)
- 100% Avalanche Tested

Absolute Maximum Ratings

Symbol	Parameter	FQP11N40C	FQPF11N40C	Units
V_{DSS}	Drain-Source Voltage	400		V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	10.5	10.5 *	A
	- Continuous ($T_C = 100^\circ\text{C}$)	6.6	6.6 *	A
I_{DM}	Drain Current - Pulsed (Note 1)	42	42 *	A
V_{GSS}	Gate-Source Voltage	± 30		V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	360		mJ
I_{AR}	Avalanche Current (Note 1)	11		A
E_{AR}	Repetitive Avalanche Energy (Note 1)	13.5		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5		V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	135	44	W
	- Derate above 25°C	1.07	0.35	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300		$^\circ\text{C}$

* Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FQP11N40C	FQPF11N40C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.93	2.86	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^\circ\text{C}/\text{W}$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQP11N40C	FQP11N40C	TO-220	--	--	50
FQPF11N40C	FQPF11N40C	TO-220F	--	--	50

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units	
Off Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	400	--	--	V	
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	--	0.54	--	$\text{V}/^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 400 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$	--	--	1	μA	
		$V_{\text{DS}} = 320 \text{ V}$, $T_C = 125^\circ\text{C}$	--	--	10	μA	
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = 30 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	--	--	100	nA	
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = -30 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	--	--	-100	nA	
On Characteristics							
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$	2.0	--	4.0	V	
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10 \text{ V}$, $I_D = 5.25 \text{ A}$	--	0.43	0.53	Ω	
g_{FS}	Forward Transconductance	$V_{\text{DS}} = 40 \text{ V}$, $I_D = 5.25 \text{ A}$	(Note 4)	--	7.1	--	
Dynamic Characteristics							
C_{iss}	Input Capacitance	$V_{\text{DS}} = 25 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$	--	840	1090	pF	
C_{oss}	Output Capacitance		--	250	325	pF	
C_{rss}	Reverse Transfer Capacitance		--	85	110	pF	
Switching Characteristics							
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}} = 200 \text{ V}$, $I_D = 10.5 \text{ A}$, $R_G = 25 \Omega$	--	14	40	ns	
t_r	Turn-On Rise Time		--	89	190	ns	
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	81	170	ns	
t_f	Turn-Off Fall Time		--	81	170	ns	
Q_g	Total Gate Charge	$V_{\text{DS}} = 320 \text{ V}$, $I_D = 10.5 \text{ A}$, $V_{\text{GS}} = 10 \text{ V}$	--	28	35	nC	
Q_{gs}	Gate-Source Charge		--	4	--	nC	
Q_{gd}	Gate-Drain Charge		--	15	--	nC	
Drain-Source Diode Characteristics and Maximum Ratings							
I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	10.5	A		
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	42	A		
V_{SD}	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 10.5 \text{ A}$	--	--	1.4	V	
t_{rr}	Reverse Recovery Time	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 10.5 \text{ A}$, $dI_F/dt = 100 \text{ A}/\mu\text{s}$	--	290	--	ns	
Q_{rr}	Reverse Recovery Charge		(Note 4)	--	2.4	--	
Notes:							
1. Repetitive Rating : Pulse width limited by maximum junction temperature							
2. $L = 5.7 \text{ mH}$, $I_{AS} = 10.5 \text{ A}$, $V_{DD} = 50 \text{ V}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$							
3. $I_{SD} \leq 10.5 \text{ A}$, $dI/dt \leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq \text{BV}_{\text{DSS}}$, Starting $T_J = 25^\circ\text{C}$							
4. Pulse Test : Pulse width $\leq 300 \mu\text{s}$, Duty cycle $\leq 2\%$							
5. Essentially independent of operating temperature							

Typical Performance Characteristics

Figure 1. On-Region Characteristics

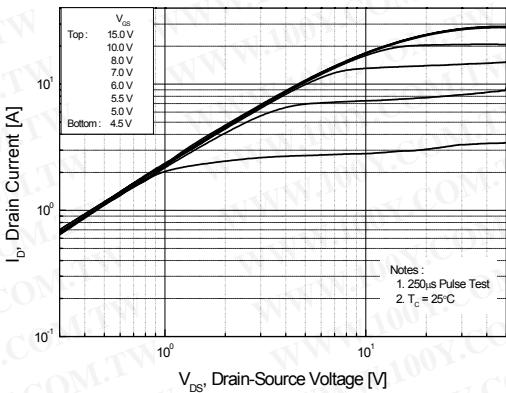


Figure 2. Transfer Characteristics

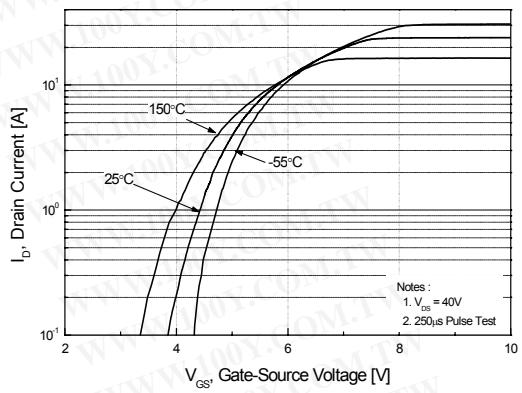


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

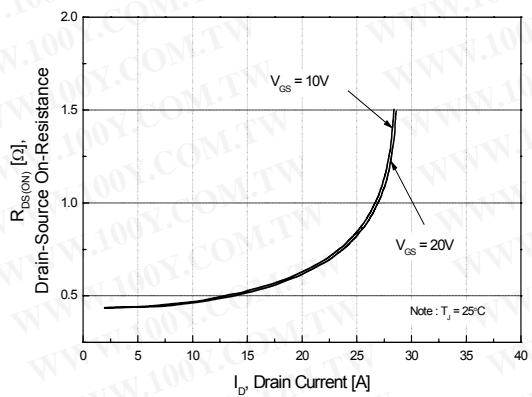


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

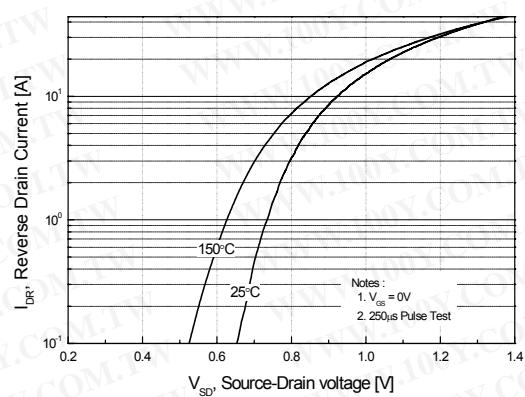


Figure 5. Capacitance Characteristics

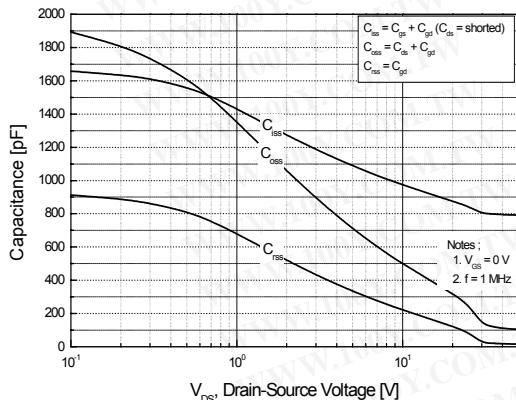
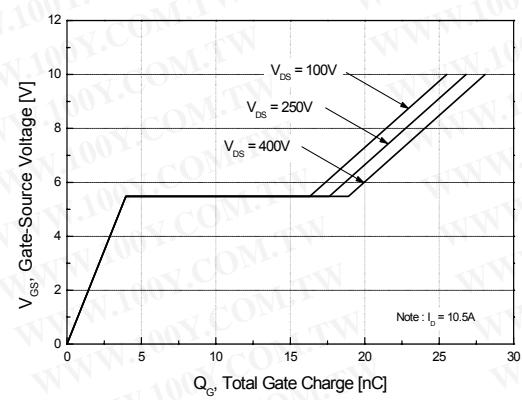


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

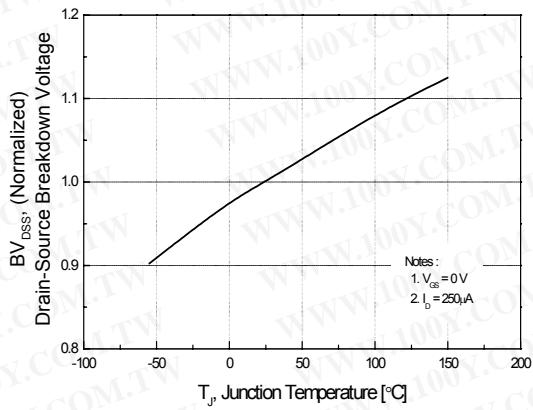


Figure 8. On-Resistance Variation vs. Temperature

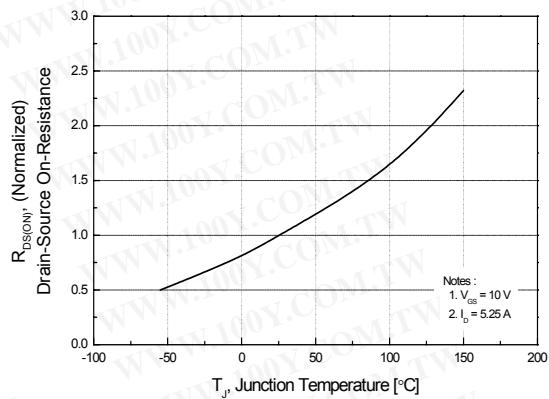


Figure 9-1. Maximum Safe Operating Area of FQP11N40C

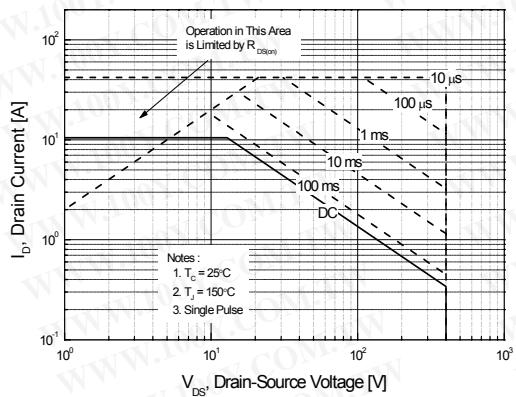


Figure 9-2. Maximum Safe Operating Area of FQPF11N40C

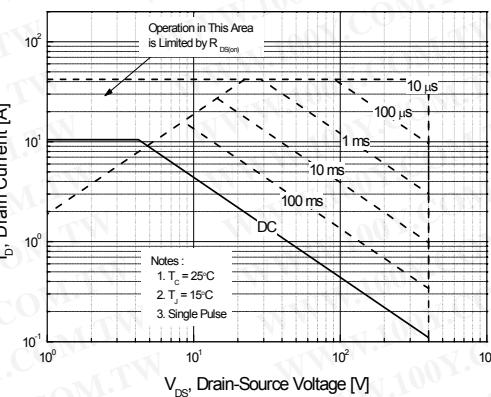
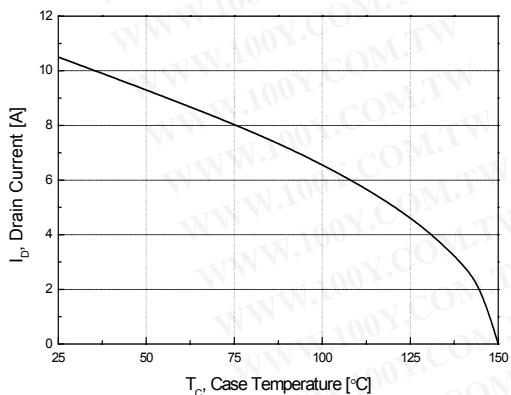


Figure 10. Maximum Drain Current



Typical Performance Characteristics (Continued)

Figure 11-1. Transient Thermal Response Curve of FQP11N40C

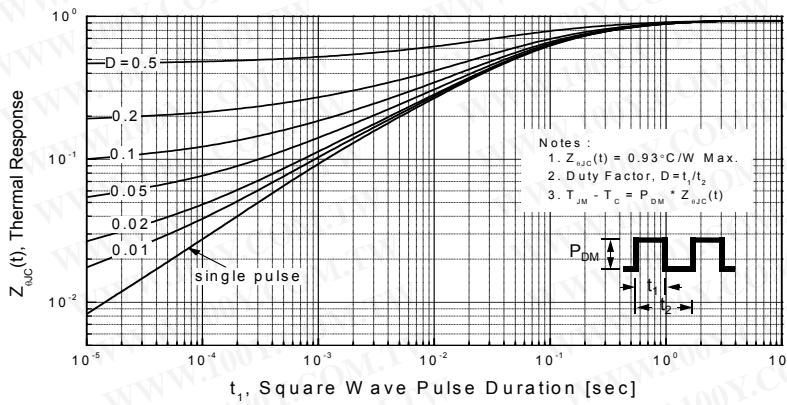
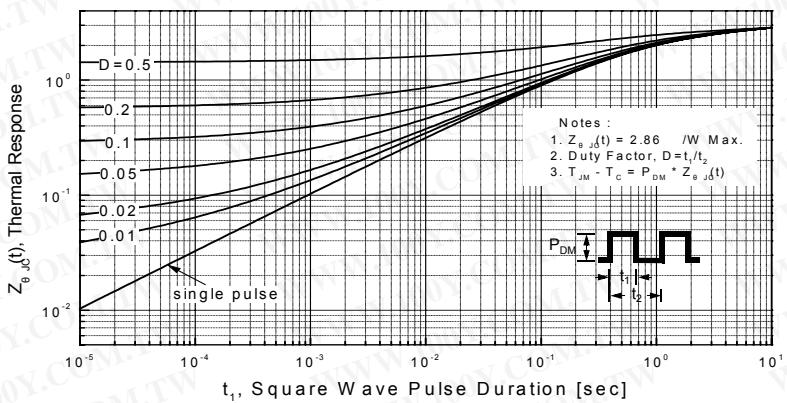
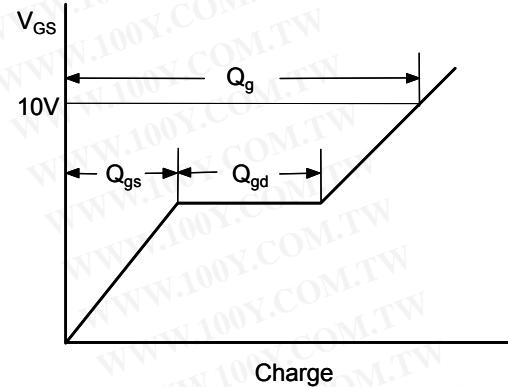
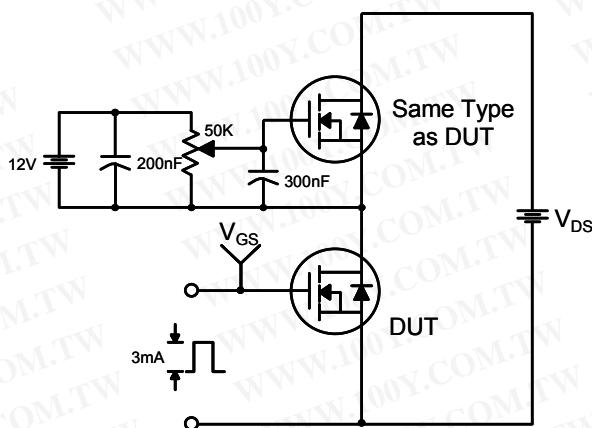


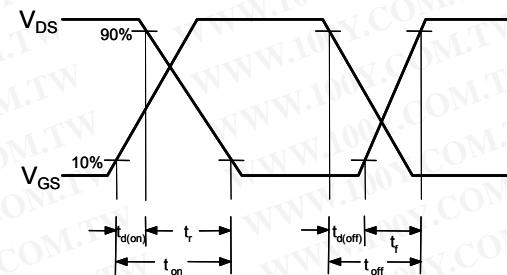
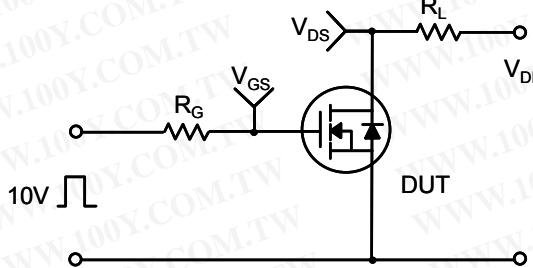
Figure 11-2. Transient Thermal Response Curve of FQPF11N40C



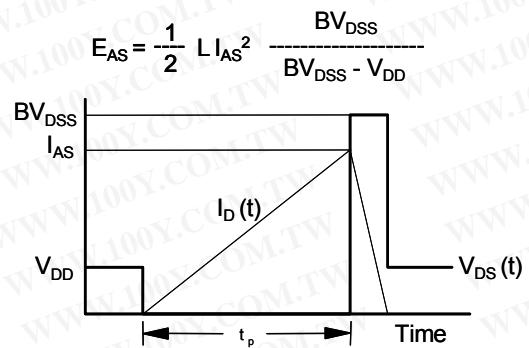
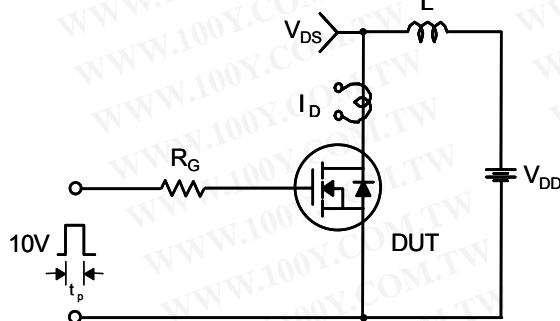
Gate Charge Test Circuit & Waveform



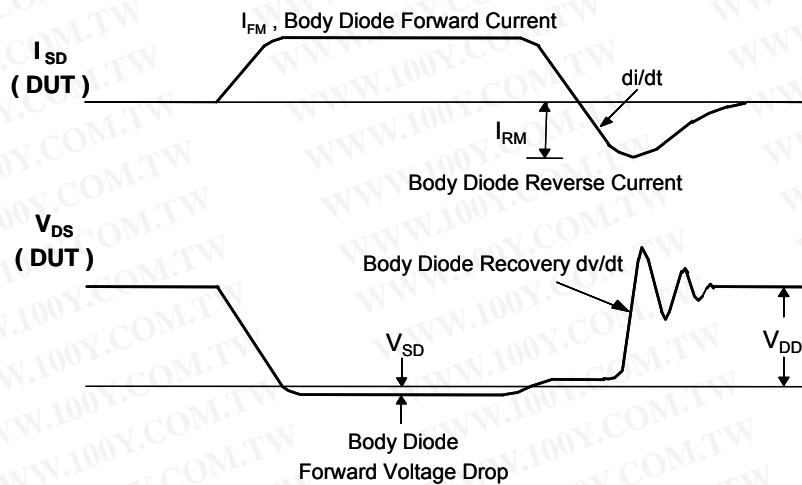
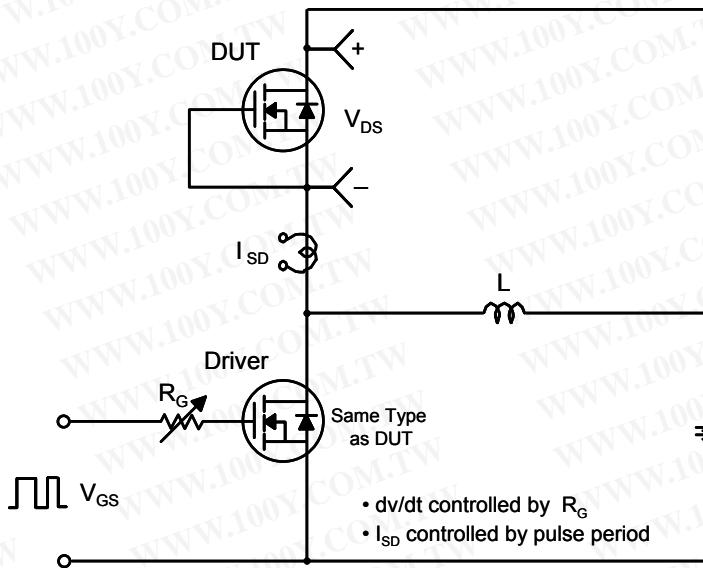
Resistive Switching Test Circuit & Waveforms

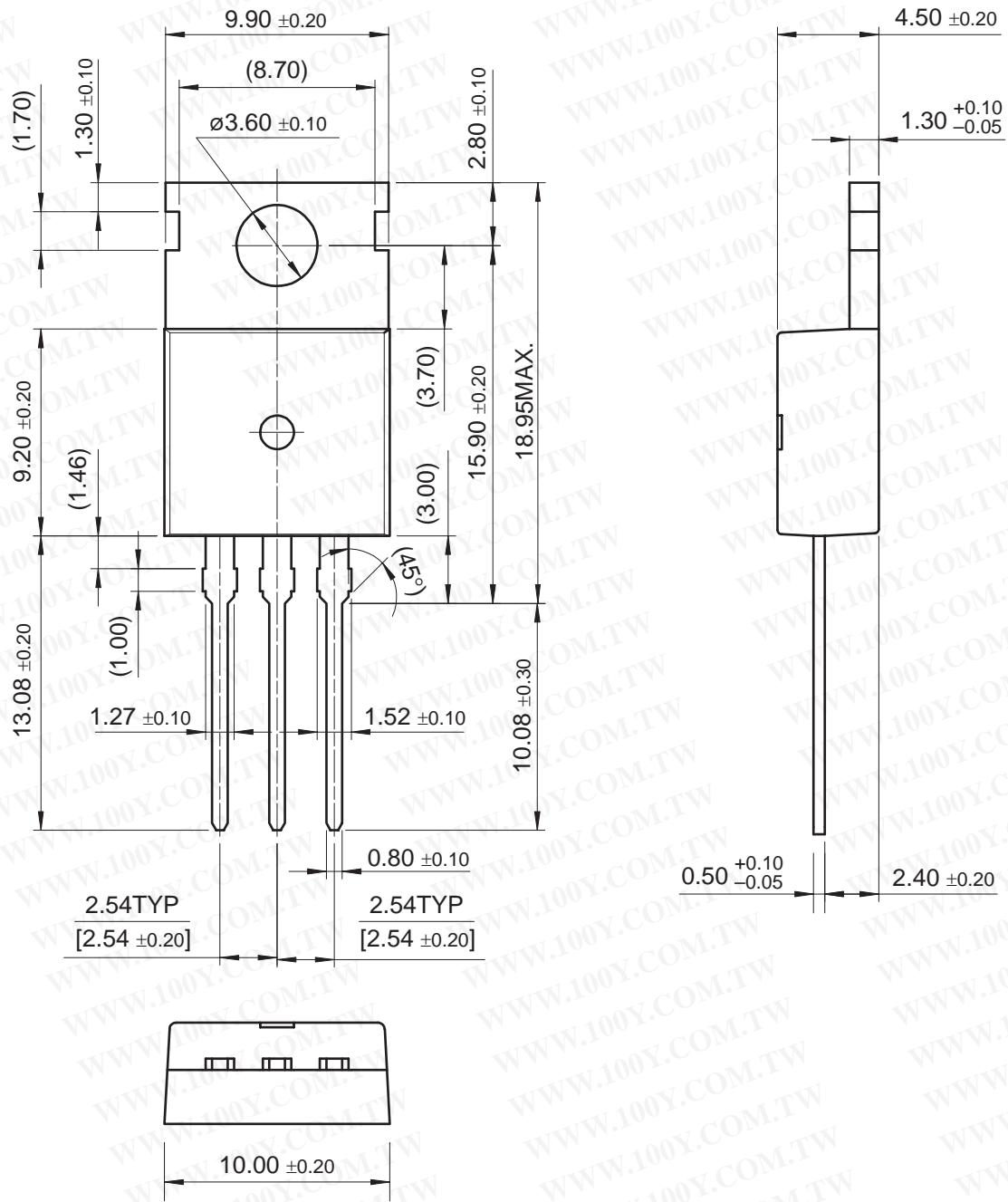


Unclamped Inductive Switching Test Circuit & Waveforms

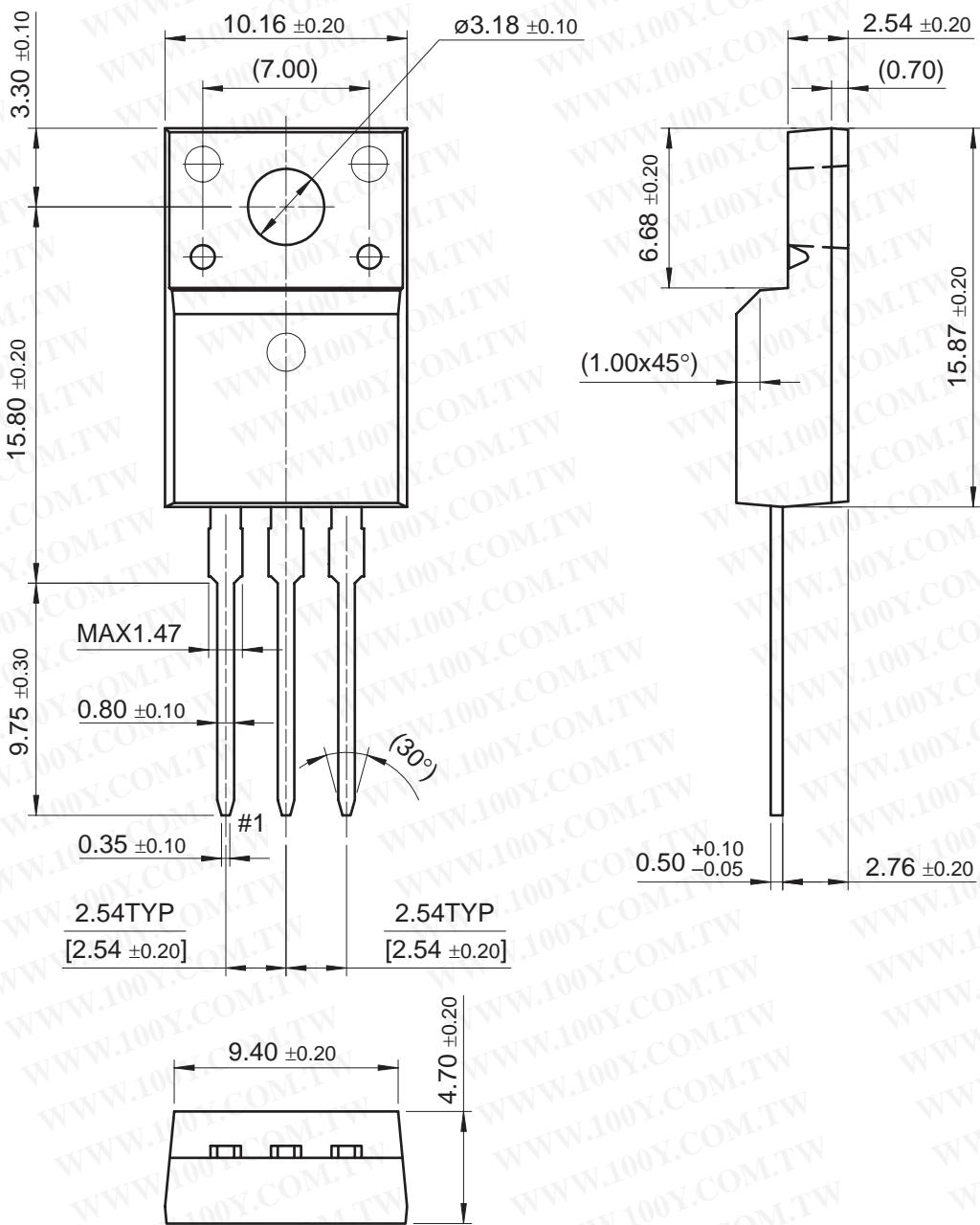


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions**TO-220**

Dimensions in Millimeters

Mechanical Dimensions (Continued)**TO-220F**

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Rev. I64